

DATA SHEET

PDTC143E series

NPN resistor-equipped transistors;

$R1 = 4.7\text{ k}\Omega$, $R2 = 4.7\text{ k}\Omega$

Product data sheet
Supersedes data of 2004 Mar 18

2004 Aug 05

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FEATURES

- Built-in bias resistors
- Simplified circuit design
- Reduction of component count
- Reduced pick and place costs.

APPLICATIONS

- General purpose switching and amplification
- Inverter and interface circuits
- Circuit driver.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V _{CEO}	collector-emitter voltage	–	50	V
I _O	output current (DC)	–	100	mA
R1	bias resistor	4.7	–	k Ω
R2	bias resistor	4.7	–	k Ω

DESCRIPTION

NPN resistor-equipped transistor (see “Simplified outline, symbol and pinning” for package details).

PRODUCT OVERVIEW

TYPE NUMBER	PACKAGE		MARKING CODE ⁽¹⁾	PNP COMPLEMENT
	PHILIPS	EIAJ		
PDTC143EE	SOT416	SC-75	02	PDTA143EE
PDTC143EEF	SOT490	SC-89	51	PDTA143EEF
PDTC143EK	SOT346	SC-59	02	PDTA143EK
PDTC143EM	SOT883	SC-101	E1	PDTA143EM
PDTC143ES	SOT54 (TO-92)	SC-43	TC143E	PDTA143ES
PDTC143ET	SOT23	–	*02	PDTA143ET
PDTC143EU	SOT323	SC-70	*02	PDTA143EU

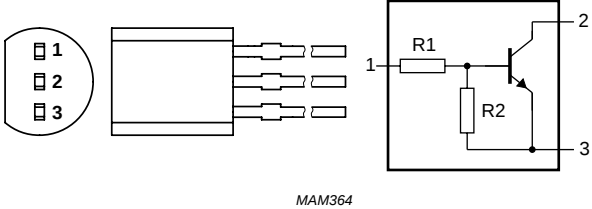
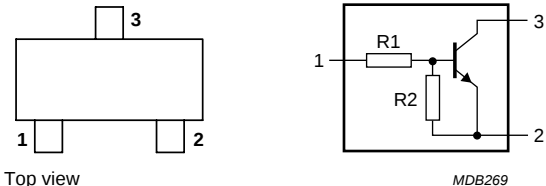
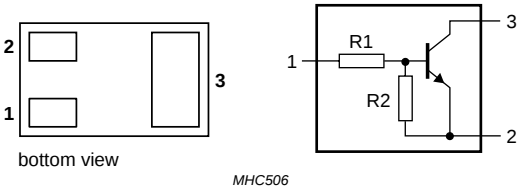
Note

- * = p: Made in Hong Kong.
* = t: Made in Malaysia.
* = W: Made in China.

NPN resistor-equipped transistors;
R1 = 4.7 kΩ, R2 = 4.7 kΩ

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SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL	PINNING	
		PIN	DESCRIPTION
PDTC143ES	 MAM364	1 2 3	base collector emitter
PDTC143EE PDTC143EEF PDTC143EK PDTC143ET PDTC143EU	 Top view MDB269	1 2 3	base emitter collector
PDTC143EM	 bottom view MHC506	1 2 3	base emitter collector

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ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PDTC143EE	–	plastic surface mounted package; 3 leads	SOT416
PDTC143EEF	–	plastic surface mounted package; 3 leads	SOT490
PDTC143EK	–	plastic surface mounted package; 3 leads	SOT346
PDTC143EM	–	leadless ultra small plastic package; 3 solder lands; body 1.0 × 0.6 × 0.5 mm	SOT883
PDTC143ES	–	plastic single-ended leaded (through hole) package; 3 leads	SOT54
PDTC143ET	–	plastic surface mounted package; 3 leads	SOT23
PDTC143EU	–	plastic surface mounted package; 3 leads	SOT323

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	–	50	V
V _{CEO}	collector-emitter voltage	open base	–	50	V
V _{EBO}	emitter-base voltage	open collector	–	10	V
V _I	input voltage				
	positive		–	+30	V
	negative		–	–10	V
I _O	output current (DC)		–	100	mA
I _{CM}	peak collector current		–	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C			
	SOT54	note 1	–	500	mW
	SOT23	note 1	–	250	mW
	SOT346	note 1	–	250	mW
	SOT323	note 1	–	200	mW
	SOT416	note 1	–	150	mW
	SOT883	notes 2 and 3	–	250	mW
	SOT490	notes 1 and 2	–	250	mW
T _{stg}	storage temperature		–65	+150	°C
T _j	junction temperature		–	150	°C
T _{amb}	operating ambient temperature		–65	+150	°C

Notes

1. Refer to standard mounting conditions.
2. Reflow soldering is the only recommended soldering method.
3. Refer to SOT883 standard mounting conditions; FR4 with 60 μ m copper strip line.

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	in free air		
	SOT54	note 1	250	K/W
	SOT23	note 1	500	K/W
	SOT346	note 1	500	K/W
	SOT323	note 1	625	K/W
	SOT416	note 1	833	K/W
	SOT883	notes 2 and 3	500	K/W
	SOT490	notes 1 and 2	500	K/W

Notes

1. Refer to standard mounting conditions.
2. Reflow soldering is the only recommended soldering method.
3. Refer to SOT883 standard mounting conditions; FR4 with 60 μ m copper strip line.

CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	V _{CB} = 50 V; I _E = 0 A	–	–	100	nA
I _{CEO}	collector-emitter cut-off current	V _{CE} = 30 V; I _B = 0 A	–	–	1	μ A
		V _{CE} = 30 V; I _B = 0 A; T _j = 150 °C	–	–	50	μ A
I _{EBO}	emitter-base cut-off current	V _{EB} = 5 V; I _C = 0 A	–	–	900	μ A
h _{FE}	DC current gain	V _{CE} = 5 V; I _C = 10 mA	30	–	–	
V _{CEsat}	collector-emitter saturation voltage	I _C = 10 mA; I _B = 0.5 mA	–	–	150	mV
V _{i(off)}	input-off voltage	I _C = 100 μ A; V _{CE} = 5 V	–	1.1	0.5	V
V _{i(on)}	input-on voltage	I _C = 20 mA; V _{CE} = 0.3 V	2.5	1.9	–	V
R1	input resistor		3.3	4.7	6.1	k Ω
$\frac{R2}{R1}$	resistor ratio		0.8	1	1.2	
C _c	collector capacitance	I _E = I _e = 0 A; V _{CB} = 10 V; f = 1 MHz	–	–	2.5	pF

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PACKAGE OUTLINES

Plastic surface-mounted package; 3 leads

SOT416

The technical drawing includes three views of the SOT416 package. The top view shows a rectangular body with three leads, with dimensions D (body width), E (lead width), and e (lead pitch). The side view shows the package height A, lead height H_E, and lead thickness c. A detail view of the lead shows dimensions A₁, L_p, and Q. A scale bar indicates 0 to 1 mm.

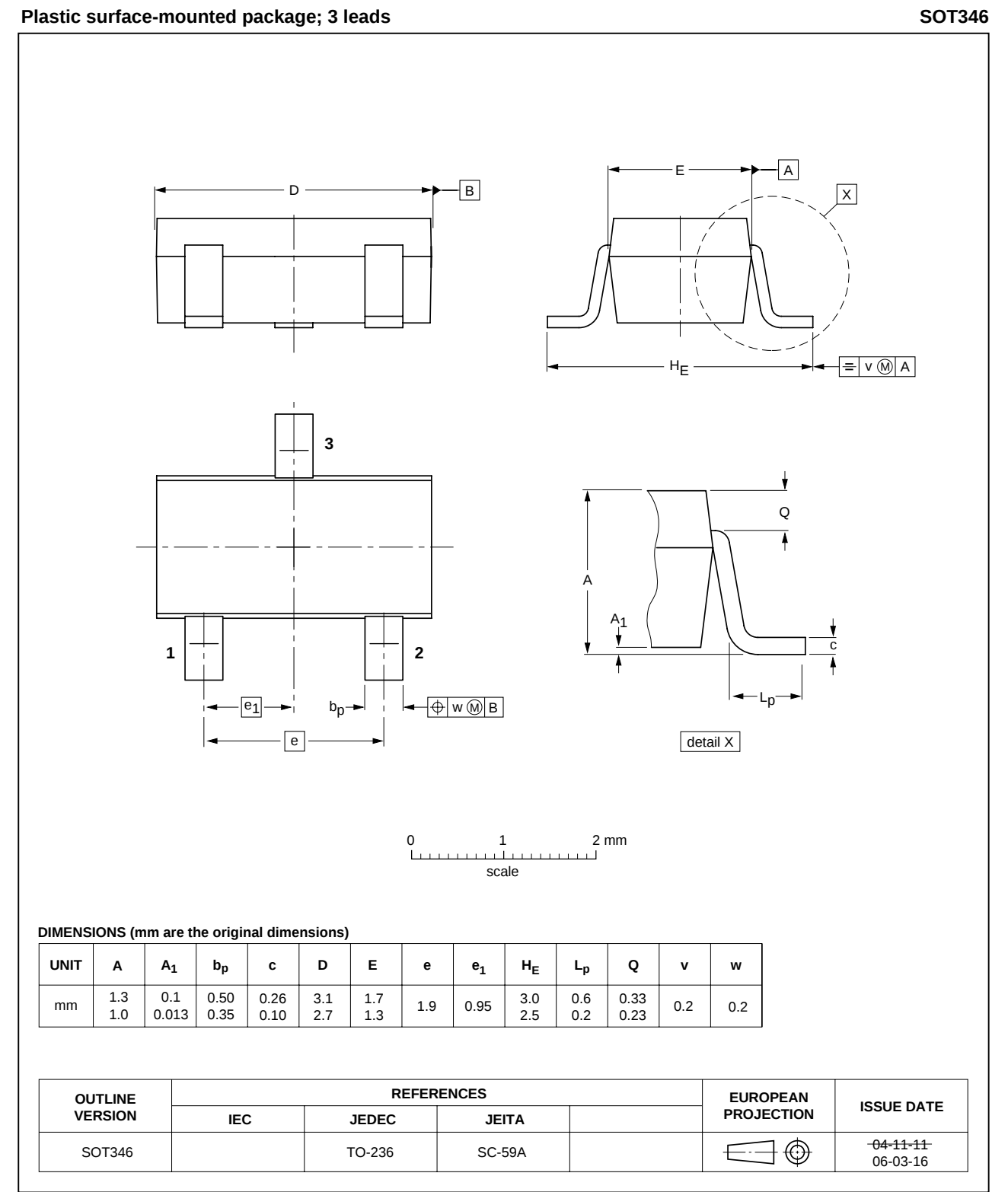
DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	0.95 0.60	0.1	0.30 0.15	0.25 0.10	1.8 1.4	0.9 0.7	1	0.5	1.75 1.45	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT416			SC-75			04-11-04 06-03-16

NPN resistor-equipped transistors;
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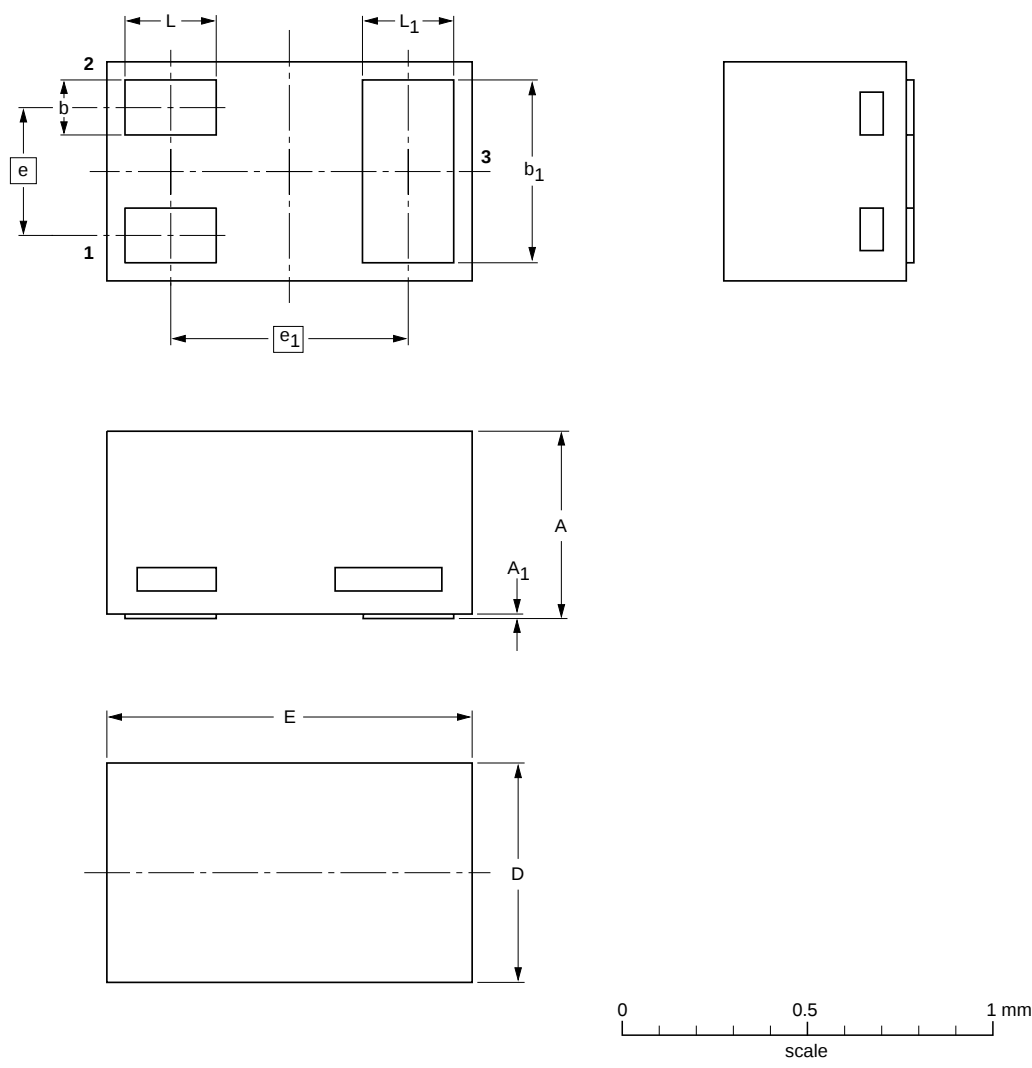


NPN resistor-equipped transistors;
R1 = 4.7 kΩ, R2 = 4.7 kΩ

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Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

SOT883



DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾	A ₁ max.	b	b ₁	D	E	e	e ₁	L	L ₁
mm	0.50 0.46	0.03	0.20 0.12	0.55 0.47	0.62 0.55	1.02 0.95	0.35	0.65	0.30 0.22	0.30 0.22

Note
1. Including plating thickness

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT883			SC-101			03-02-05 03-04-03

NPN resistor-equipped transistors;
R1 = 4.7 kΩ, R2 = 4.7 kΩ

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Plastic single-ended leaded (through hole) package; 3 leads

SOT54

Technical drawing of the SOT54 package showing top, side, and lead detail views with dimension labels A, b, b₁, c, D, d, E, e, e₁, L, L₁.

0 2.5 5 mm
scale

DIMENSIONS (mm are the original dimensions)

UNIT	A	b	b ₁	c	D	d	E	e	e ₁	L	L ₁ ⁽¹⁾ max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

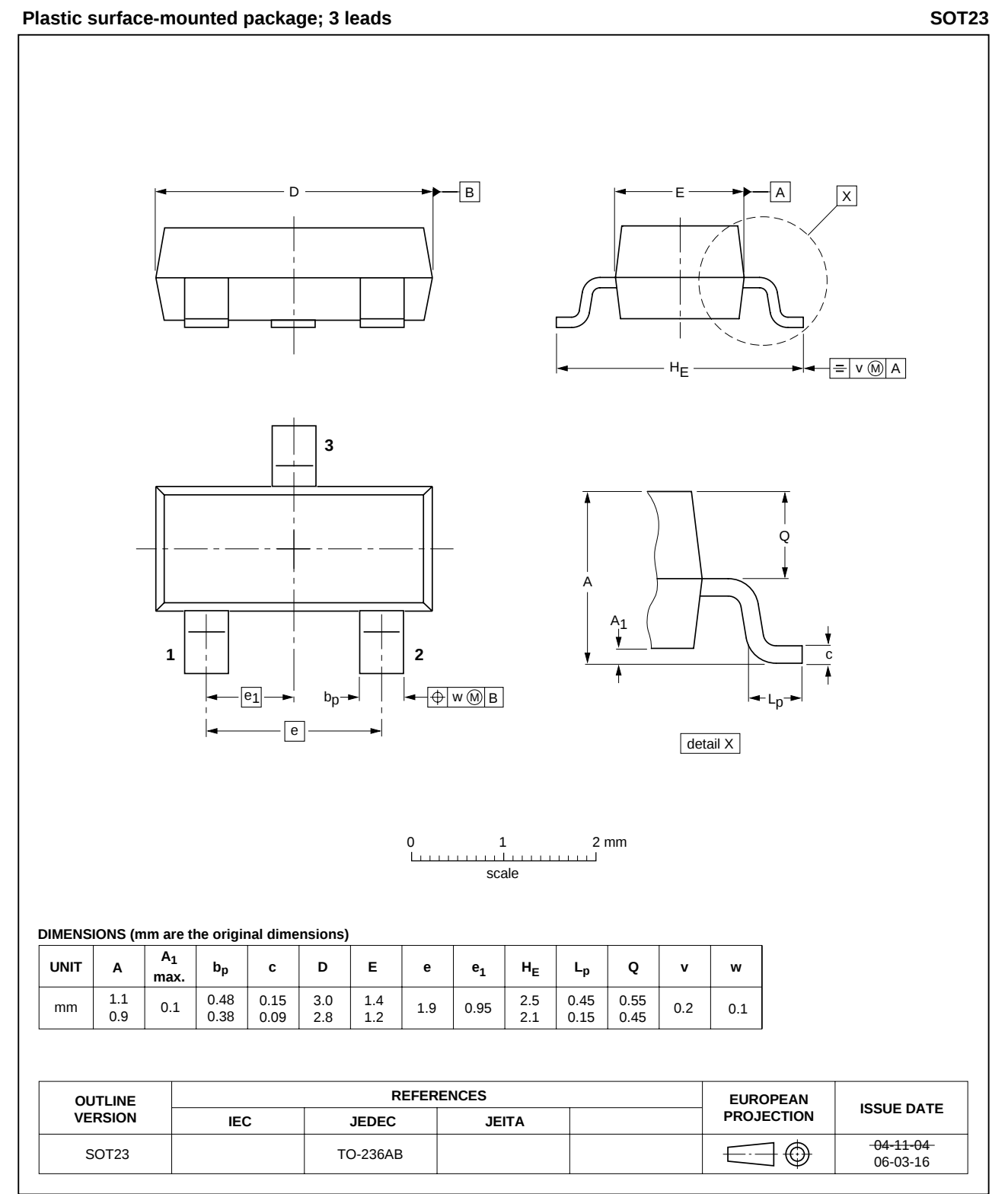
Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT54		TO-92	SC-43A			04-06-28 04-11-16

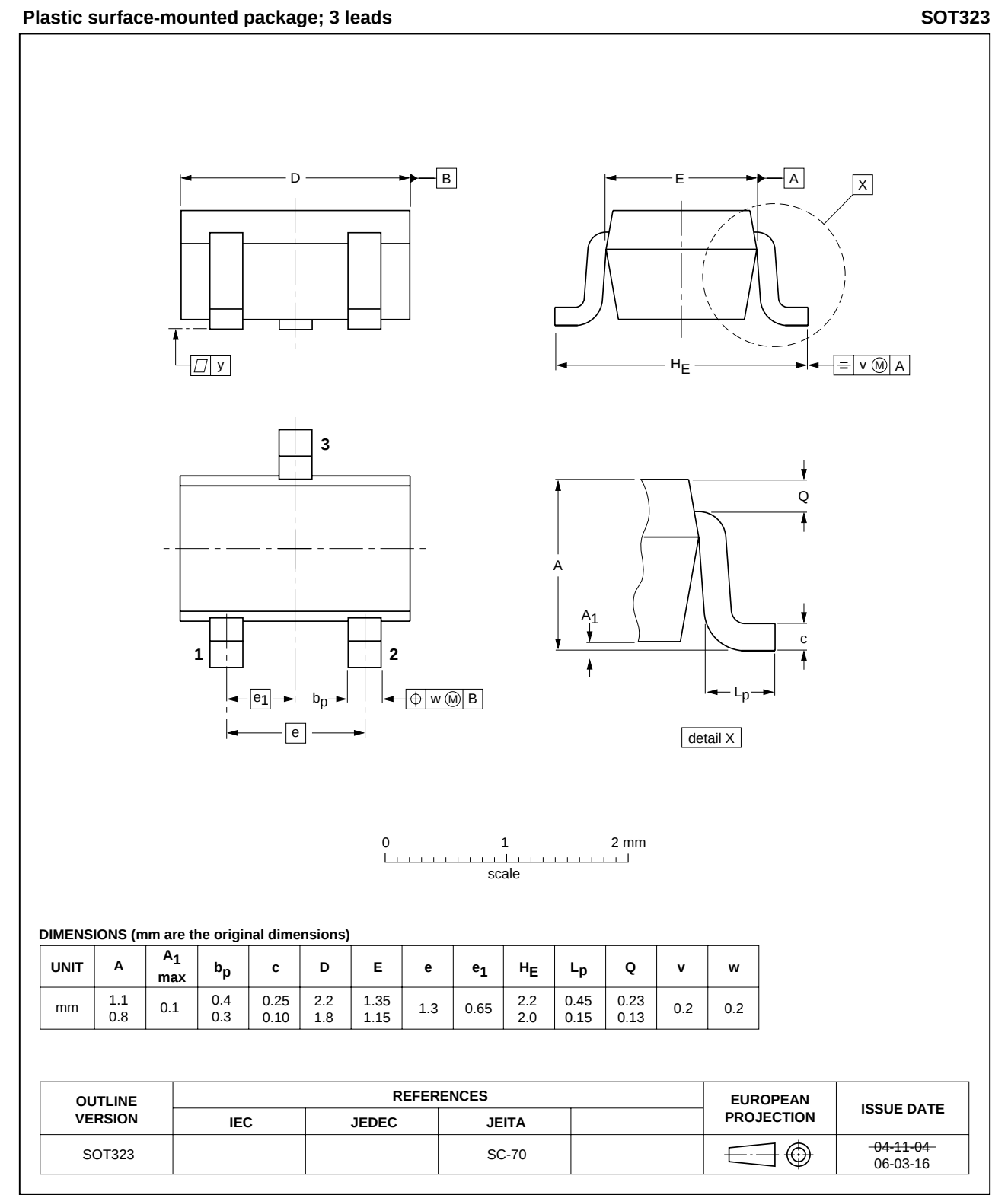
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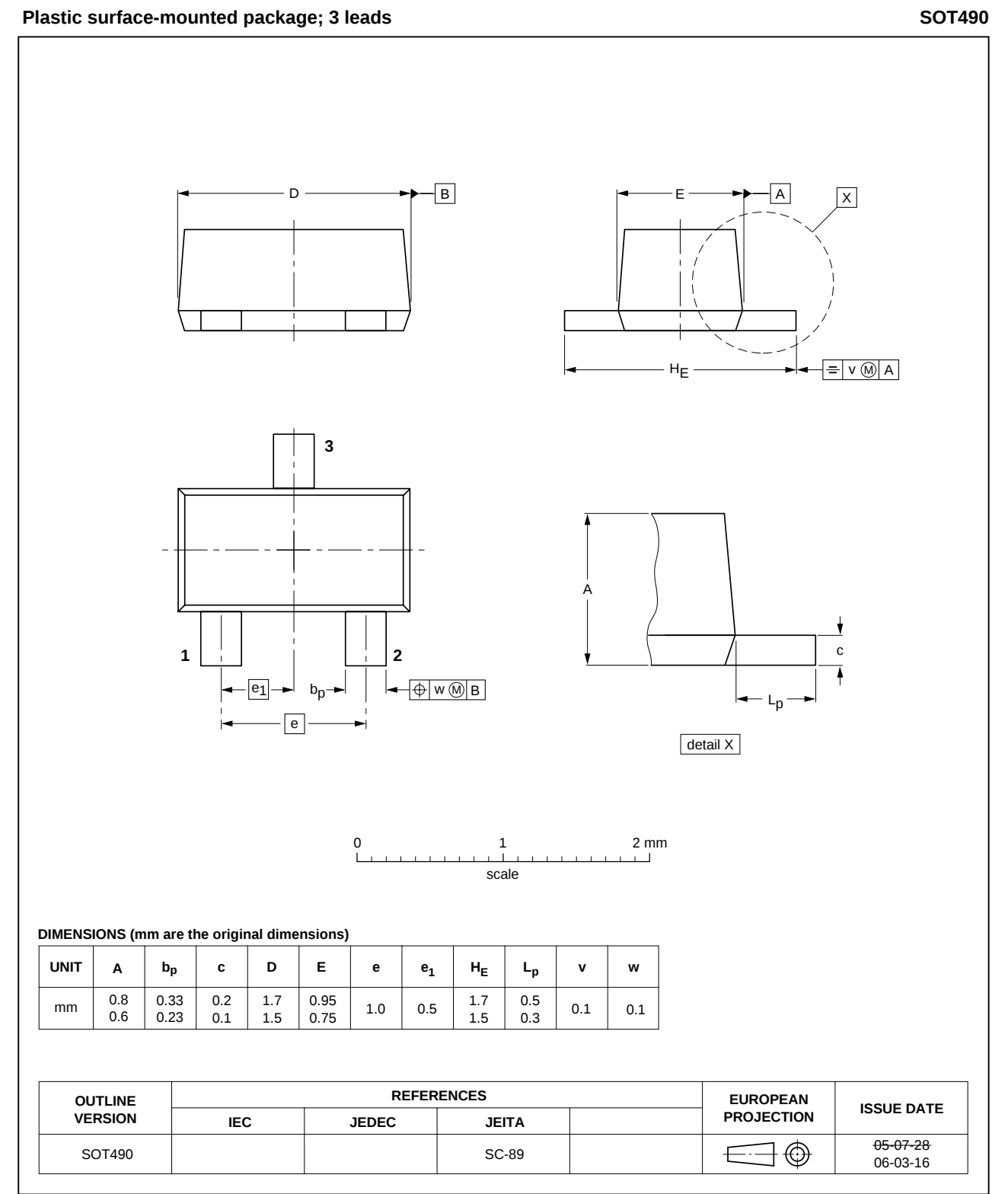
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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: **<http://www.nxp.com>**

For sales offices addresses send e-mail to: **salesaddresses@nxp.com**

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